INFORMATION DISCLOSURE CITATION

Docket: 015559-288	Appln. No.: 10/620,119
Applicant: Thomas Wiegele et al.	
Filed: July 15, 2003	Group: 2874

Page 1 of 3 Pages

U.S. PATENT DOCUMENTS

Examiner		Document No.	Date	Name	Class	Sub	
		2003/0107794	06/2003	Siekkinen et al.			
TM		6,525,864	02/2003	Gee et al.			
TM		6,449,079	09/2002	Herrmann			
TM		6,291,317	09/2001	Salatino et al.			
TM		5,923,995	07/1999	Kao et al.			
TM		5,721,162	02/1998	Schubert et al.			

FOREIGN PATENT DOCUMENT

Examiner		Document No.	Date	Country	Class	Sub	Trans Y	Trans N
TM		06-120336 (with English abstract)	04/1994	Japan				X
TM		08-106614 (with English abstract)	04/1996	Japan				X

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

TM		Graph of cure time vs. glass transition temperature for BCB (date unknown) Applicants admit the status of this graph as prior art for the limited purpose of examination of this application, but otherwise reserve the right to challenge the status of this publication as prior art.
TM		Statement by Applicants (including Attachment A)
TM		M. Jenkins, et al., "Chemical and Structural Characterization of Silane Adhesion Promoting Films for Use in Microelectronic Packaging, Materials Research Society. Symp. Vol. 629, pp. FF5.12.1-FF5.12.6 (2000)

Examiner: [signature] Date Considered: 05/2005

*Examiner: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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		F. Niklaus, et al., "Low-Temperature Wafer-Level Transfer Bonding," Journal of Microelectromechanical Systems, Vol. 10, No. 4, pp. 525-531 (12/2001)
TM		F. Niklaus, et al., "Void-Free Full Wafer Adhesive Bonding," Department of Signals, Sensors and Systems, Royal Institute of Technology, Stockholm, Sweden (date unknown) Applicants admit the status of this publication as prior art for the limited purpose of examination of this application, but otherwise reserve the right to challenge the status of this publication as prior art.
TM		S.K. Sampath, et al., "Rapid MEMS Prototyping using SU-8, Wafer Bonding and Deep Reactive Ion Etching," IEEE (2001)
TM		A. Jourdain, et al., "Investigation of the Hermeticity of BCB-Sealed Cavities for Housing (RF-)MEMS Devices," IEEE, pp. 677-680 (2002)
TM		T-K. Chou et al., "3D MEMS Fabrication Using Low-Temperature Wafer Bonding with Benzocyclobutene (BCB)," The 11th International Conference on Solid-State Sensors and Actuators, Munch, Germany (6/2001)
TM		J. Neysmith et al., "A Modular, Chip Scale, Direct Chip Attach MEMS Package: Architecture and Processing," The International Journal of Microcircuits and Electronic Packaging, Vol. 23, No. 4, pp. 474-480 (2000)
TM		P.V. Dressendorfer, et al., "MEMS Packaging – Current Issues and Approaches," 2000 International Conference on High-Density Interconnect and System Packaging (2000)
TM		Product literature entitled "CYCLOTENE™ 4000 Series Advanced Electronic Resins (Photo BCB) – Processing Procedures for Cyclotene 4000 Series (Photo BCB Resins DS2100 Puddle Develop Process," CYCLOTENE™ Advanced Electronic Resins, by Dow (revised 5/03/1999)
TM		Product literature entitled "CYCLOTENE™ 4000 Series Advanced Electronic Resins (Photo BCB) – Processing Procedures for CYCLOTENE™ 4000 Series Photo BCB Resins – Immersion Develop Process," CYCLOTENE™ Advanced Electronic Resins, by Dow (revised 4/02/2001)
TM		Product literature entitled "Cure and Oxidation Measurements for Cyclotene Advanced Electronic Resins," CYCLOTENE™ Advanced Electronic Resins, by Dow (date unknown) Applicants admit the status of this publication as prior art for the limited purpose of examination of this application, but otherwise reserve the right to challenge the status of this publication as prior art.

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M		G. Mittendorfer, et al., "Summary Study of BCB Coating Tests," by EVG (date unknown) Applicants admit the status of this publication as prior art for the limited purpose of examination of this application, but otherwise reserve the right to challenge the status of this publication as prior art.
M		"Tutorial 1 – Introduction to Flip Chi;p: What, Why, How," web page by Flip Chips Dot Com (date of first publication unknown). Applicants admit the status of this publication as prior art for the limited purpose of examination of this application, but otherwise reserve the right to challenge the status of this publication as prior art.
M		S. Renard, "Wafer level Surface Mountable Chip Size Packaging for MEMS and ICs," Micromachined Devices and Components VI, Proceedings of SPIE, Vol. 4176 (2000)
M		H.H. Gatzen, "Dicing challenges in microelectronics and micro electro-mechanical systems (MEMS)," Microsystem Technologies, 7, pp. 151-154 (2001)
M		H.H. Gatzen, et al., "Advances in Dicing Wafers for Micro Electro-Mechanical Systems (MEMS)," Proceedings Volume 2, MICRO.tec 2000, Hanover Germany (9/2000)

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